

A 3D rendering of various cable assemblies and connectors. The background features several blue flat-flex cables extending from the top towards the bottom. In the foreground, there are several black plastic connectors of different shapes and sizes, some with gold-plated pins. One connector is a large rectangular one with many pins, another is a smaller one with a different pin configuration, and there are also some smaller, more complex connectors. The overall scene is set against a blue gradient background.

Cable Assembly Modeling

samtec

Audio Information for today's presentation

- Dial: 1-800-944-8766 (US)
- Dial: 1-317-713-0002 (Outside of US)
- Use Conference Code 61969

Cable Assembly Models for SPICE Simulation

June 29, 2006

11:00am EST

Duration: 1 hour

Outline

- **Motivation for Developing Cable Assembly Models**
- **Lossy Transmission Lines**
- **Developing the Cable Assembly Model**
- **Using the Cable Assembly Model**
- **Useful Resources**

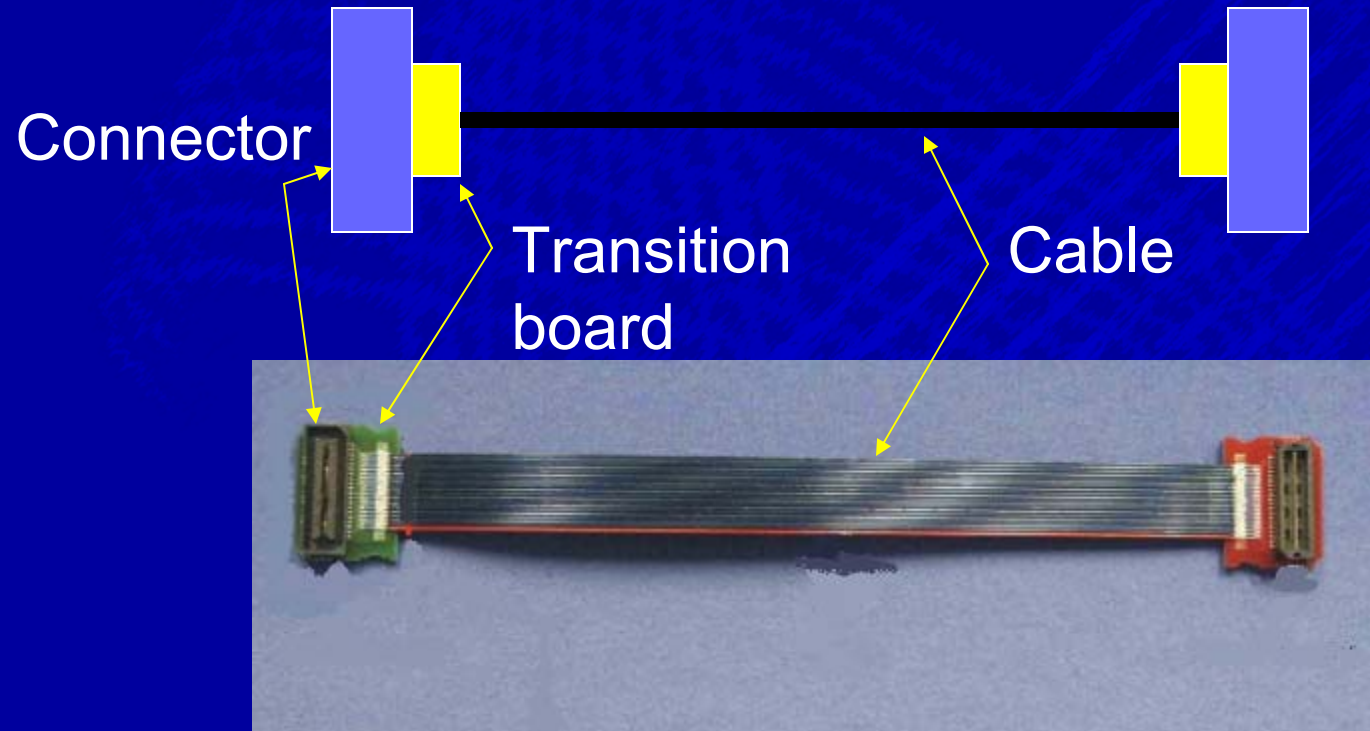
Motivation for Developing Cable Assembly Models

- **Our Customers Request Them!**
 - Emphasis is on Customer Service [easy]
 - ♦ We logged 1,500 SI service requests in 2005
 - Requests are for SPICE, IBIS or S-Parameter models of connectors and cable assemblies

Motivation for Developing Cable Assembly Models

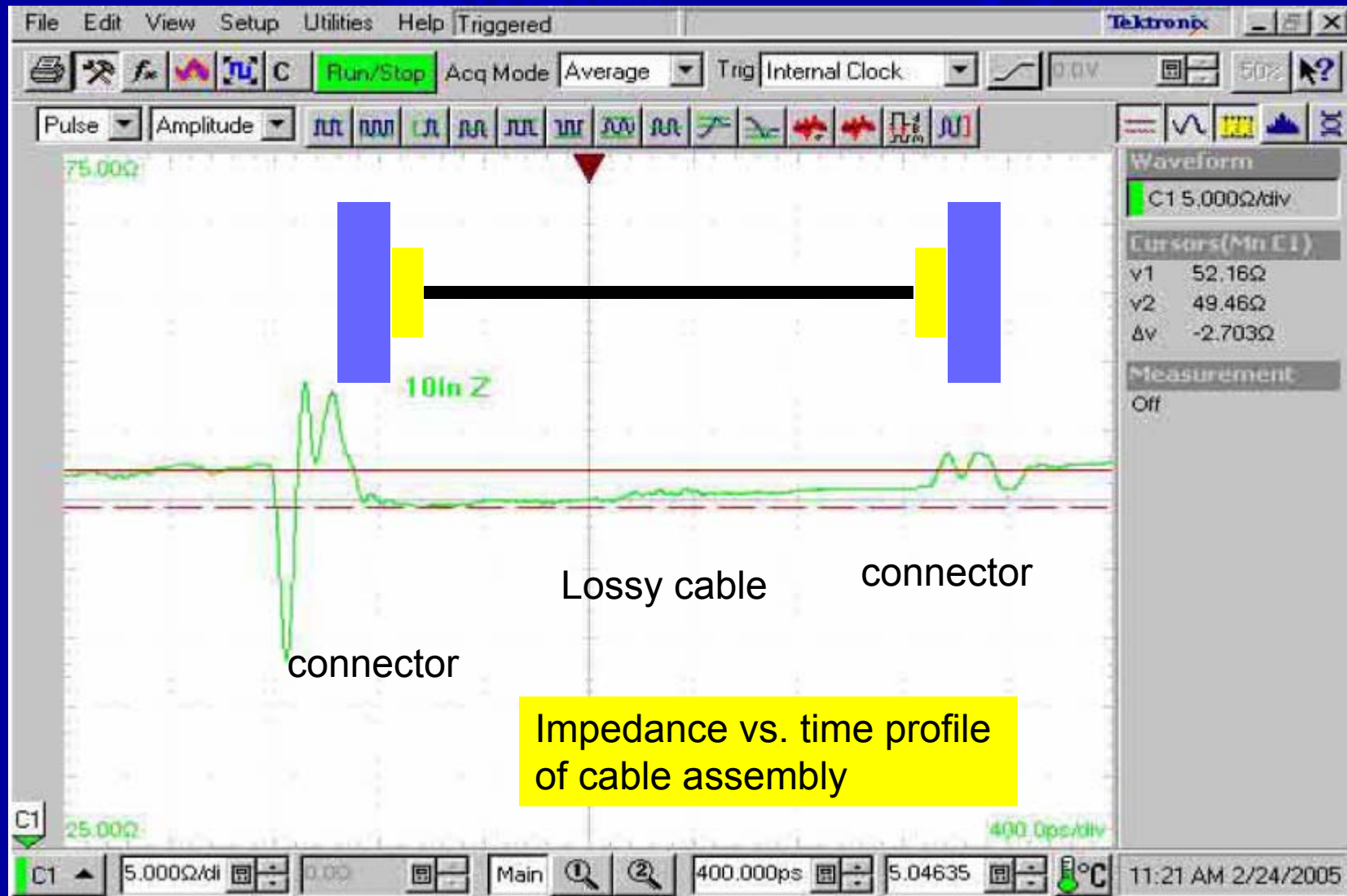
- **Integral to Design Decisions**
 - What AWG cable is required?
 - What length cable will work?
 - ♦ What is the frequency response?
 - ♦ What does the eye pattern look like at "x" Gbps?

Developing the Cable Assembly Model



- The cable assembly does not always have a transition board, but it will always have a transition area from cable to connector

Developing the Cable Assembly Model



Developing the Cable Assembly Model

- **Approach - Collection of models**
 - Raw cable
 - Connectors
 - Transition/paddle boards
- **As opposed to a measured S-Parameter library which is not length scalable, modular, or useable in generic SPICE**

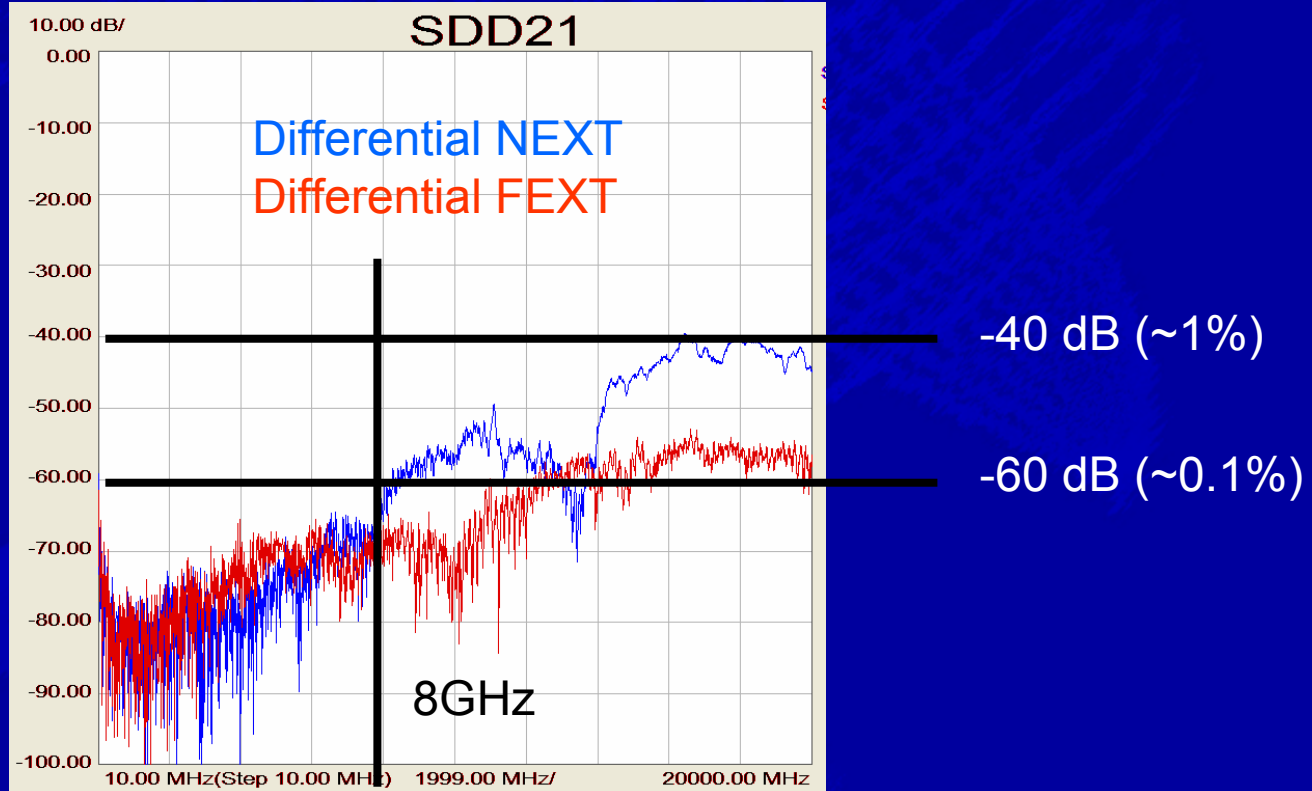
Developing the Cable Assembly Model

- **Assumptions**

- Valid for risetimes of 50 ps or slower
 - ◆ Determined by the complexity of paddleboard and connector model
- Crosstalk in the cable is zero

Developing the Cable Assembly Model - Raw Cable

- Assumptions
 - No crosstalk in the cable



Measured differential crosstalk in 30AWG ribbonized twinax

Lossy Transmission Lines

- Lossless transmission line

- Impedance

$$Z_0 = \sqrt{\frac{L}{C}}$$

- Prop Delay

$$t_{pd} = \frac{d\sqrt{\epsilon_r}}{c}$$

- Output Risetime

$$t_{out} = t_{in}$$

- Lossless transmission lines are well described by simple equations

Lossy Transmission Lines

- **Lossy transmission line** (actually the low-loss approximation)

- Impedance

$$Z_0 = \sqrt{\frac{R + j\omega L}{G + j\omega C}}$$

- Group Delay

$$GD = \frac{d\phi}{dt}$$

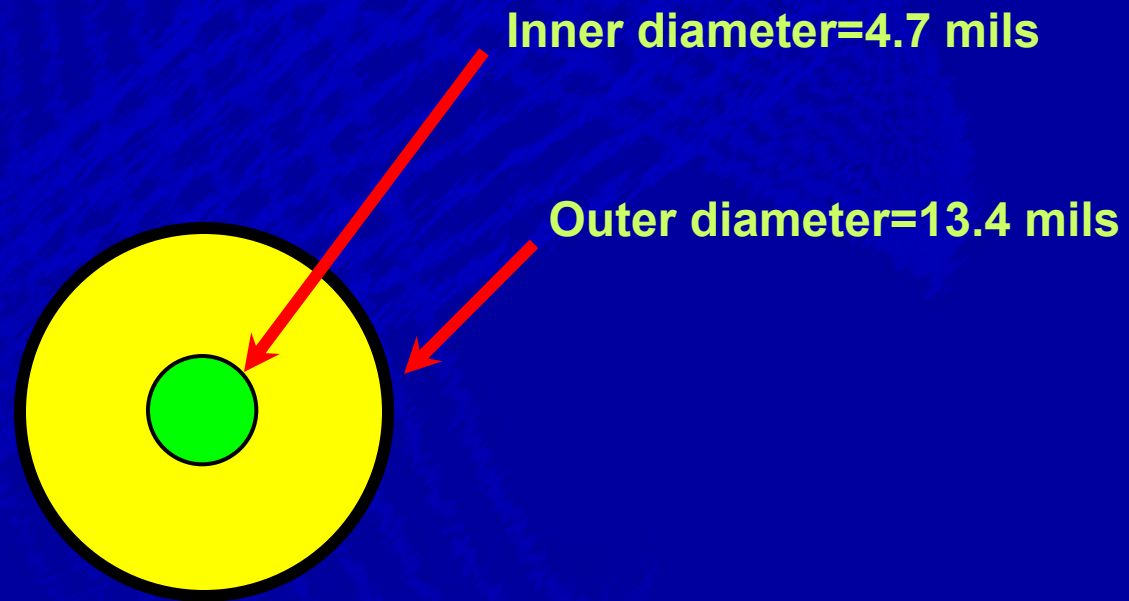
- Step Response Time

$$t_r \approx \frac{0.35}{BW}$$

- **Lossy transmission lines are much more complex to describe with simple equations in the time domain. Low loss approximations are the normal.**

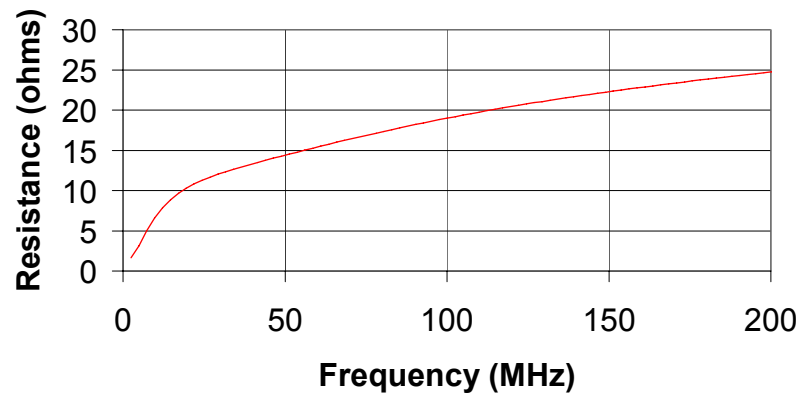
Lossy Transmission Lines

- To illustrate lossy cable behavior, consider a 38 AWG Coax
- Extract the RLGC parameters for this cable using IConnect

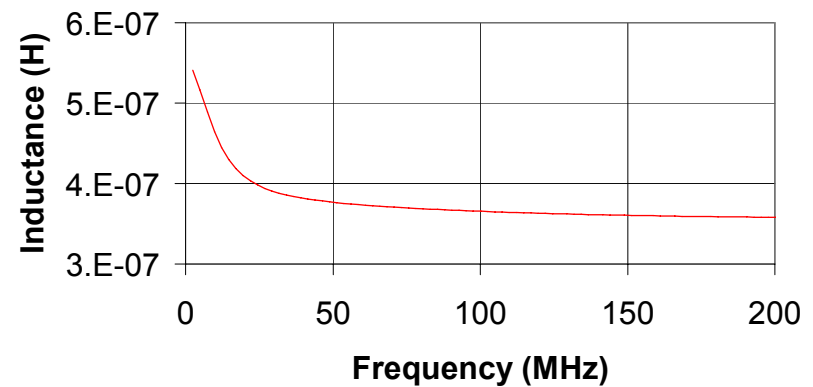


RLGC Behavior for 38 AWG Coax Cable

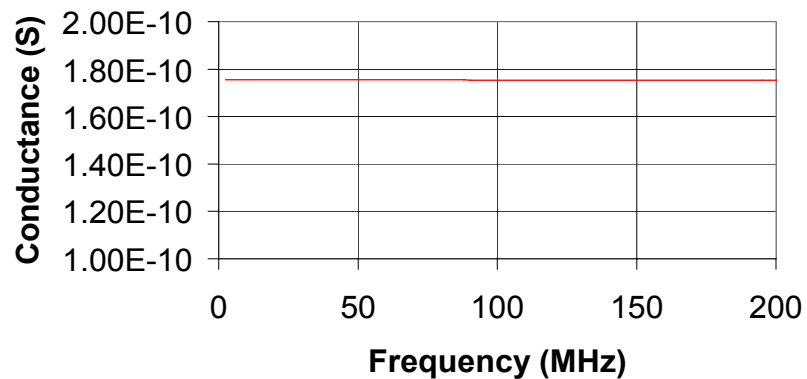
R vs F



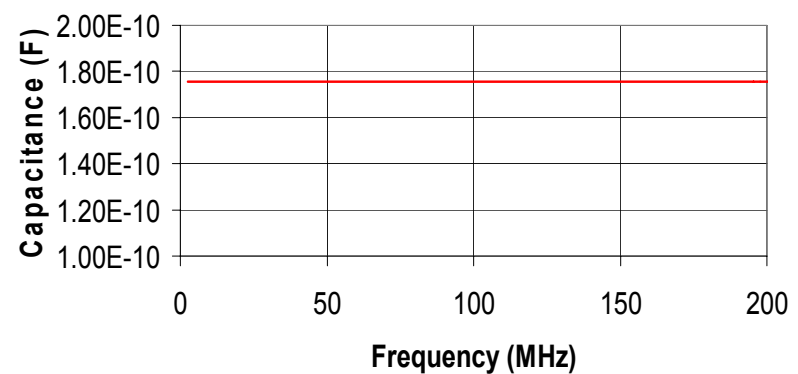
L vs F



G vs F

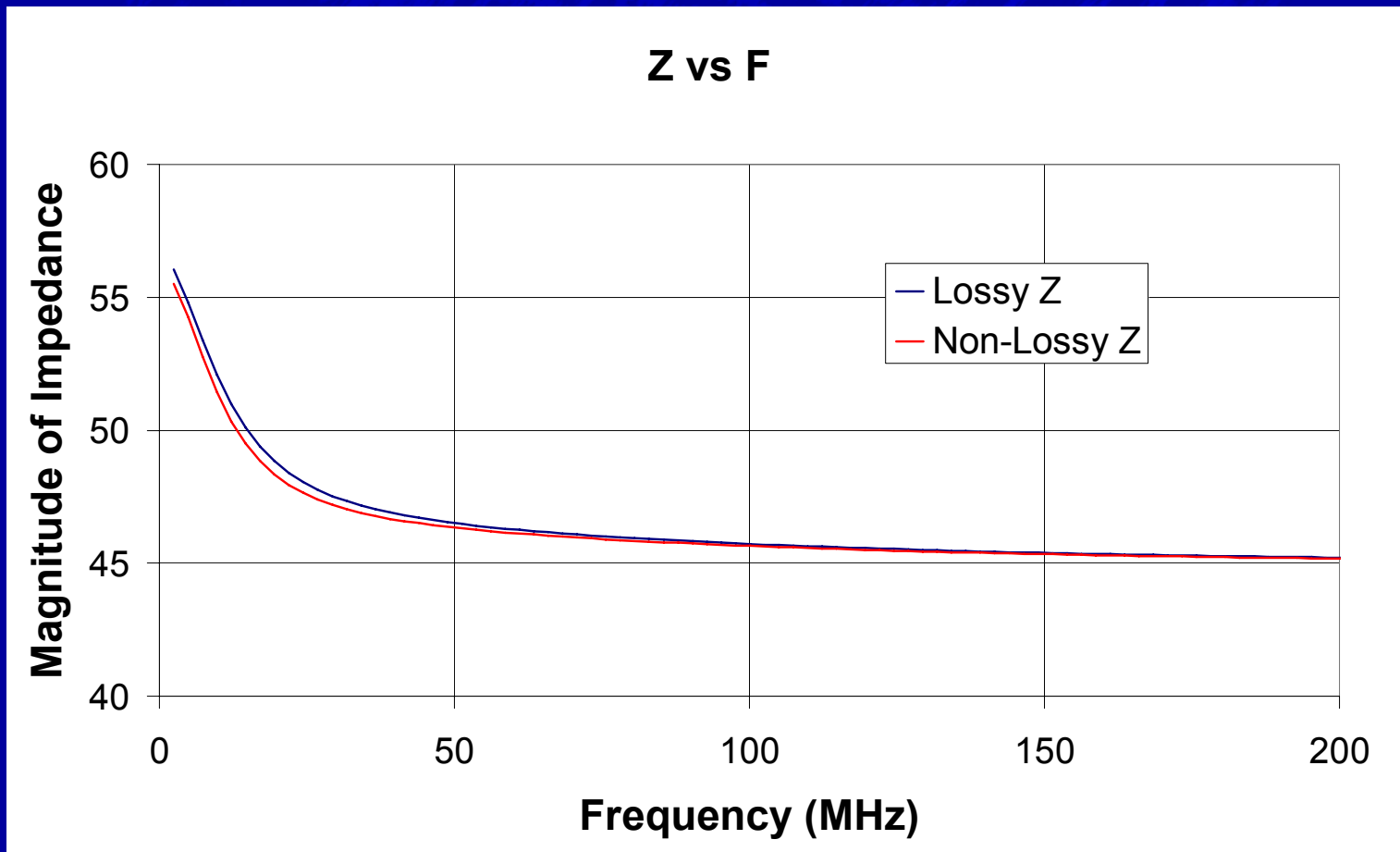


C vs F



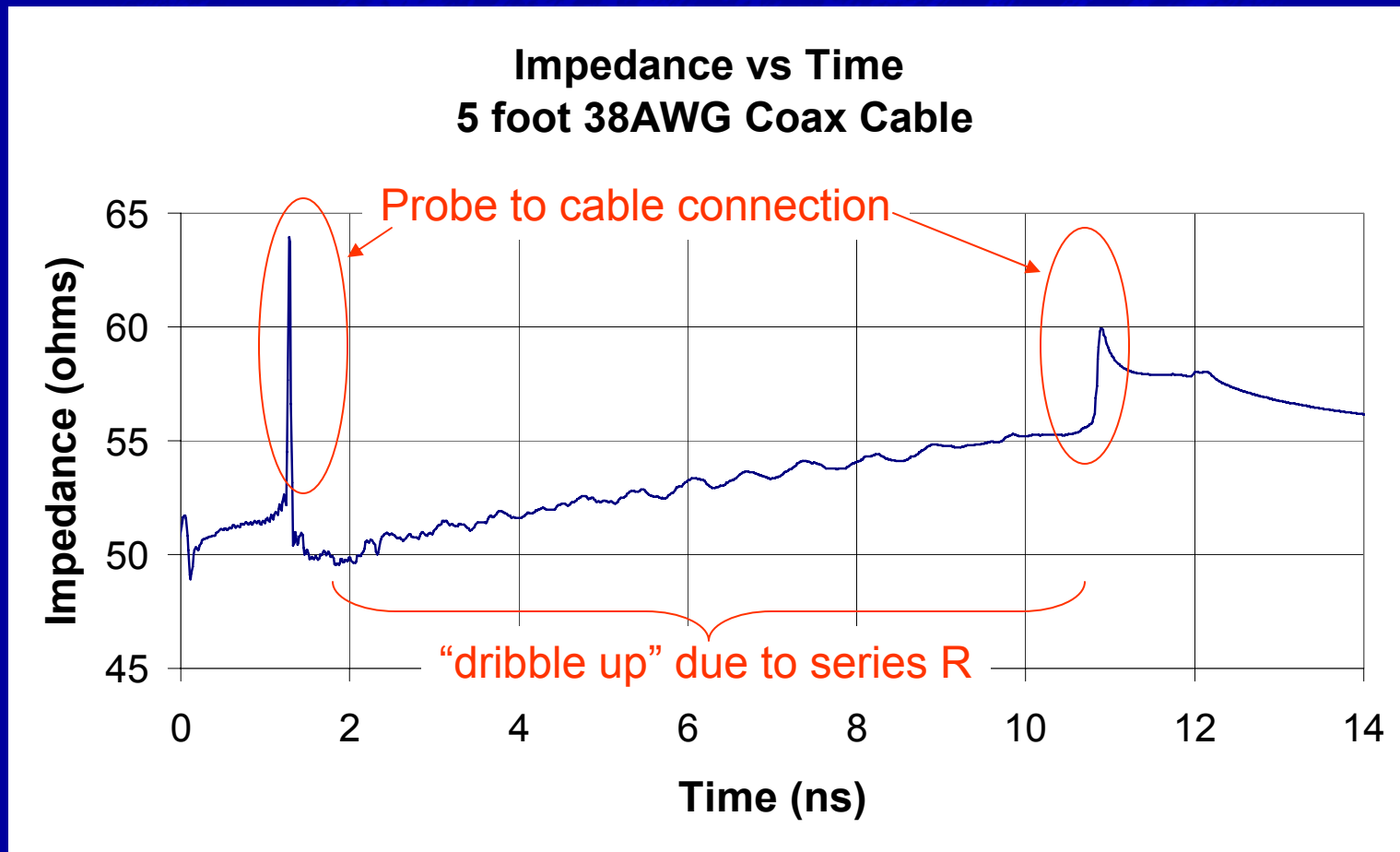
Lossy Transmission Lines

- Characteristic Impedance



Lossy Transmission Lines

- TDR profile showing lossy response

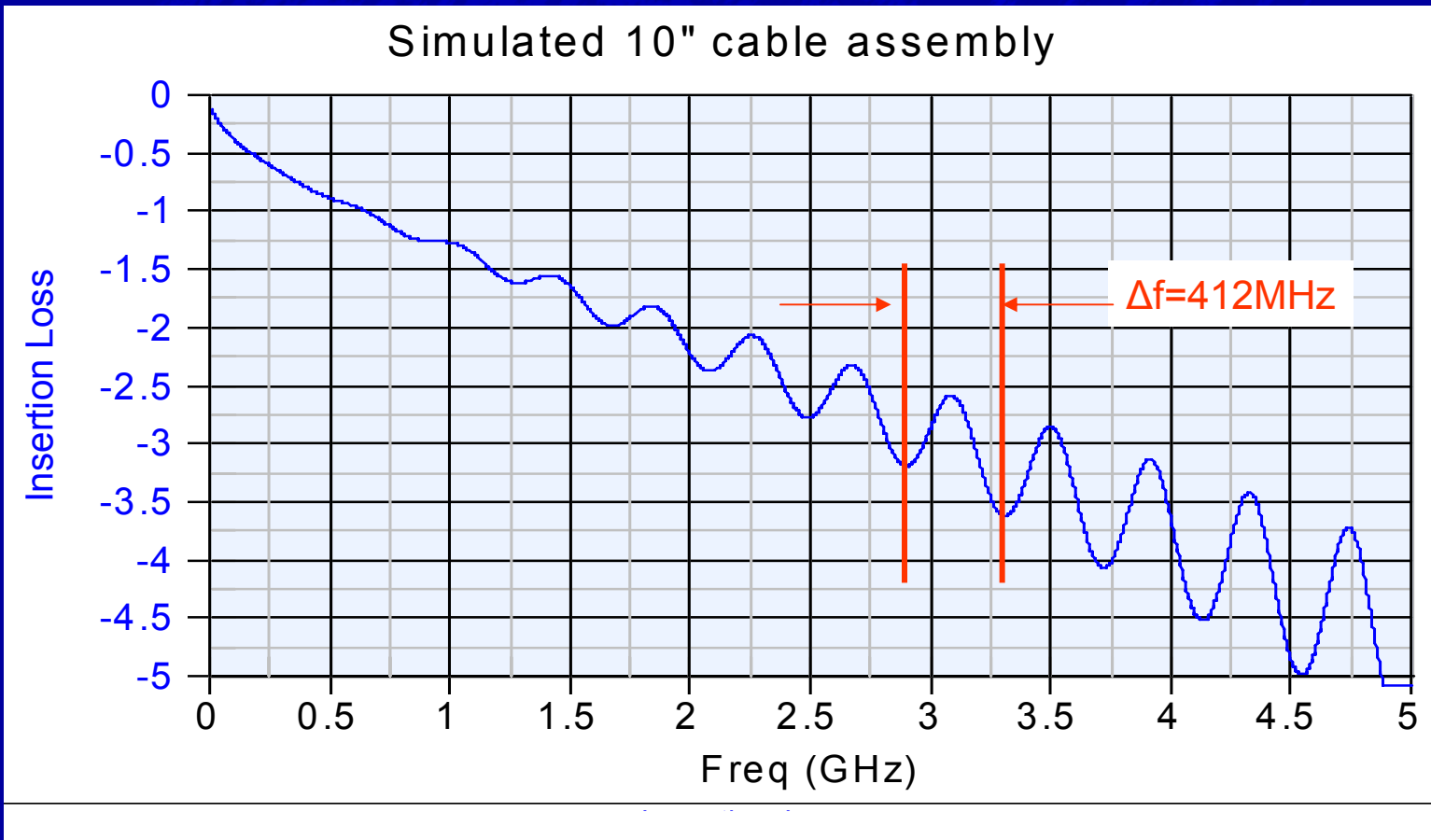


Lossy Transmission Lines

▪ Summary

- R and L change (significantly at lower frequency)
- Characteristic Impedance varies with frequency
 - ♦ Higher at low frequency
 - ♦ Skin effect cause R and L to vary
 - ♦ Change in L with frequency dominates characteristic impedance behavior
- Resistance causes “dribble up” on TDR profile

Resonance Effects and Length

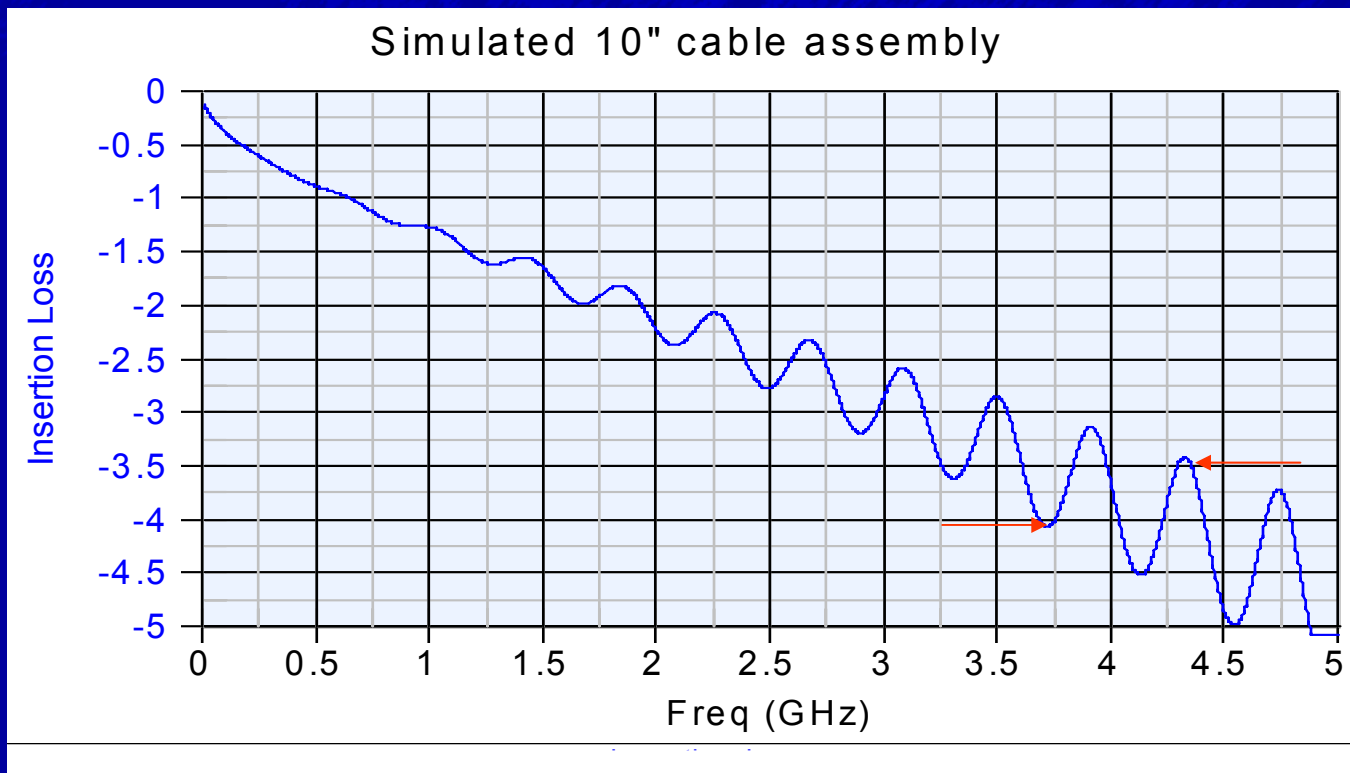


Resonance Effects and Length

- Impedance mismatch from connectors cause ripple in the insertion loss profile at $l=\lambda/2$
- For a 10'' cable assembly with $\epsilon_r=2$, $\Delta f=V_p/\lambda$
 - ϵ_r =relative dielectric constant
 - V_p =phase velocity
 - λ =wavelength
 - Δf =frequency spacing between nulls in insertion loss profile
- $\Delta f=412$ MHz (refer to previous slide)

Resonance Effects and Length

- Resonance effects tend to be more pronounced in low loss (short) cable assemblies
- Explains why cable assembly loss can be greater at lower frequency
- A length scalable model allows users to easily investigate resonance behavior



S-Parameters

- **Measurement based model can be developed with frequency domain tools**
 - Vector Network Analyzer
 - ◆ Export a Touchstone model (S-Parameters)
 - ◆ De-embed fixturing effects
 - HSPICE can operate with Touchstone models
 - ◆ Reasonable simulation times
- **But care must be taken using S-Parameters in a time domain simulation...**

S-Parameters

- **Passivity**

- Passive network cannot show energy gain
- Passivity violations not uncommon when de-embedding test board effects

- **Causality**

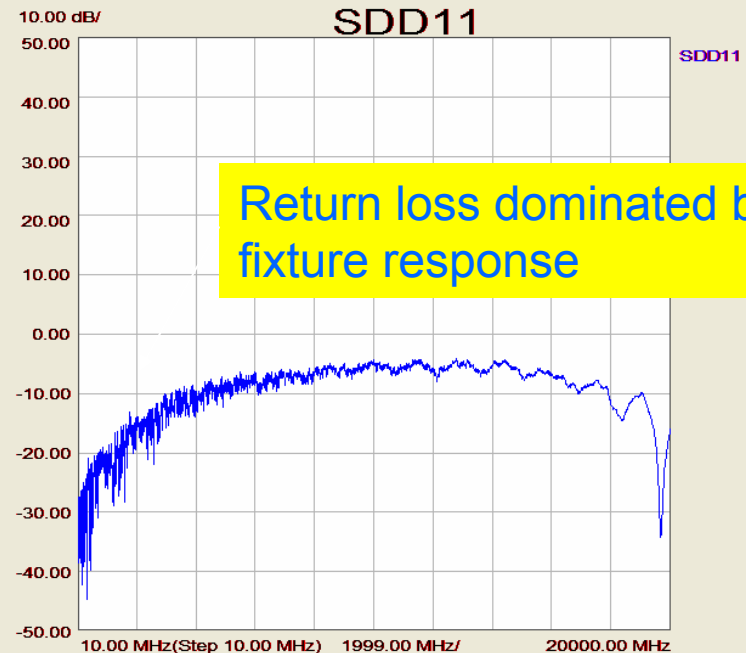
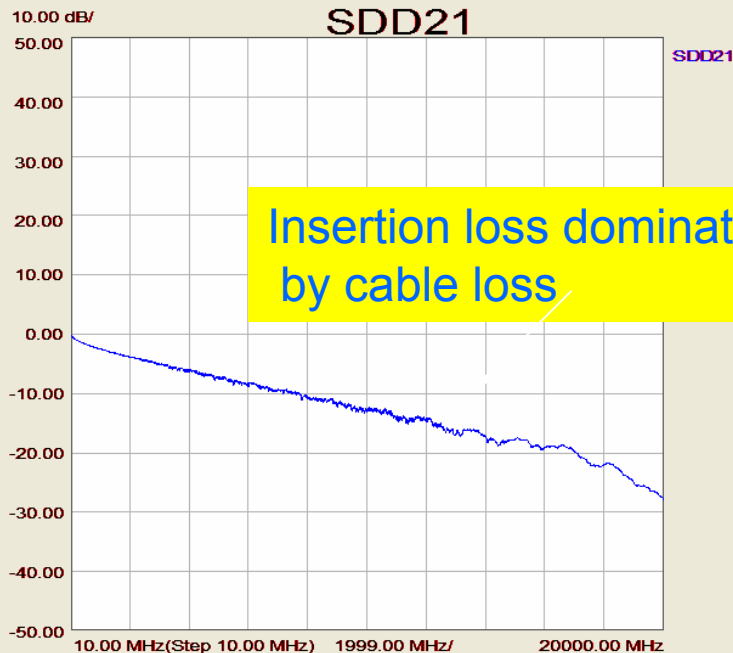
- Output response vs. prop delay
- Kramers-Kronig Relationship (loss tangent must change with frequency for broadband simulations)
- Dielectric modeling becomes involved

- **Symmetry**

- For a 2 port network, $S_{21}=S_{12}$
- VNA Calibration errors can result in asymmetric behavior

Real Data Response

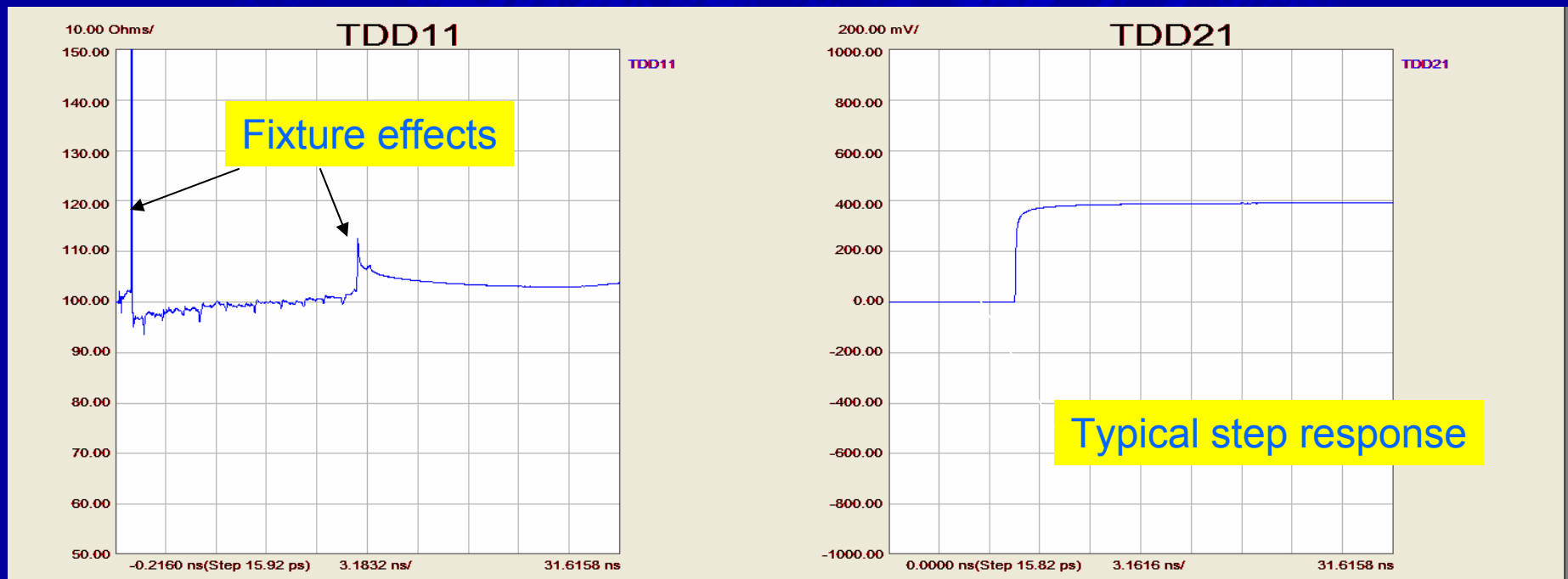
- 30 AWG Twinax with test fixtures
 - 10MHz-20GHz, 10MHz step



Differential insertion and return loss from measurements

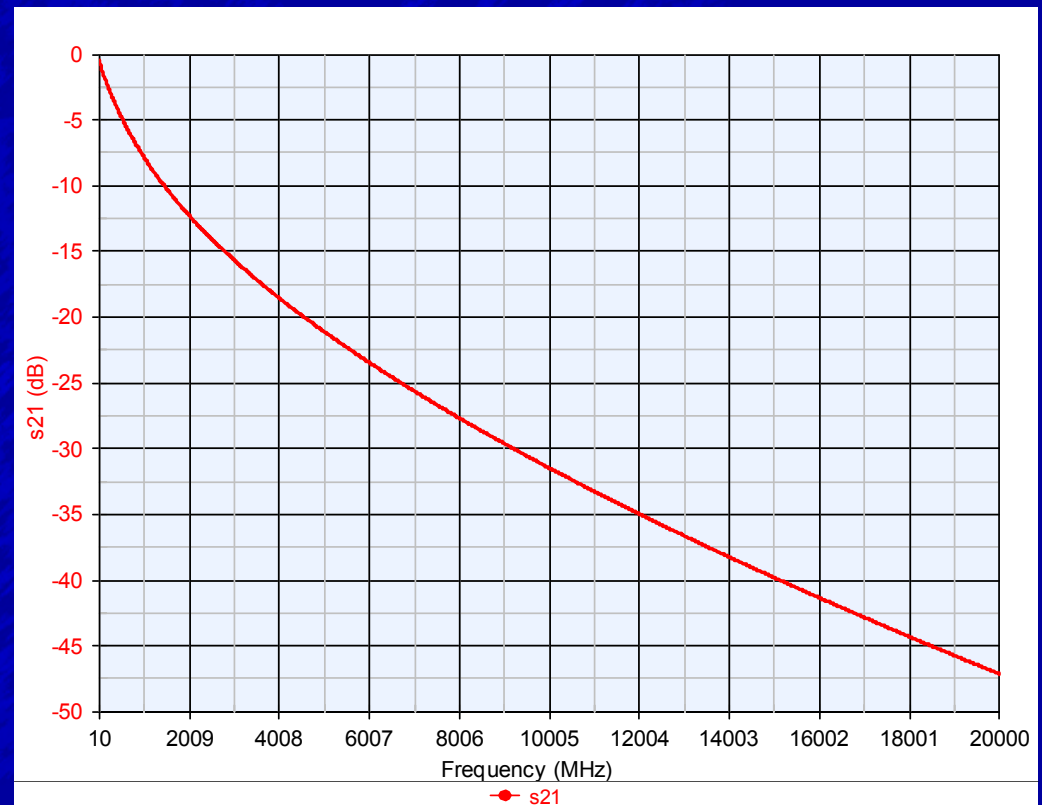
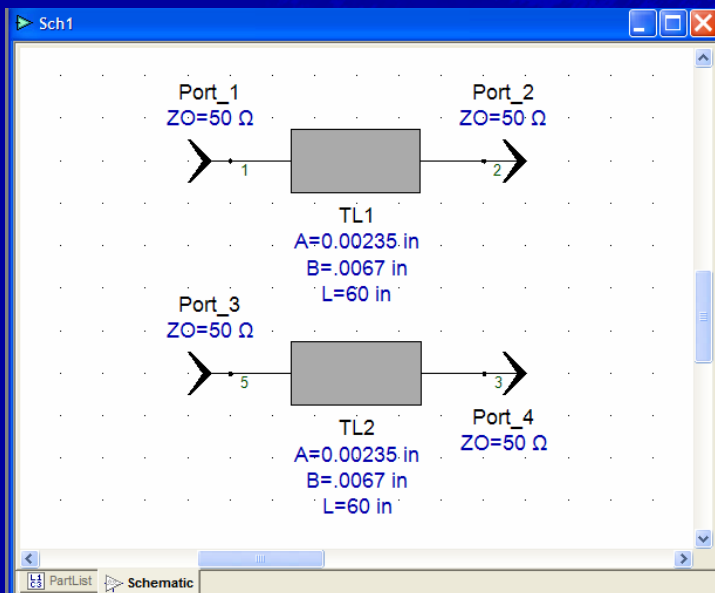
Real Data Response

- 30 AWG Twinax with test fixtures
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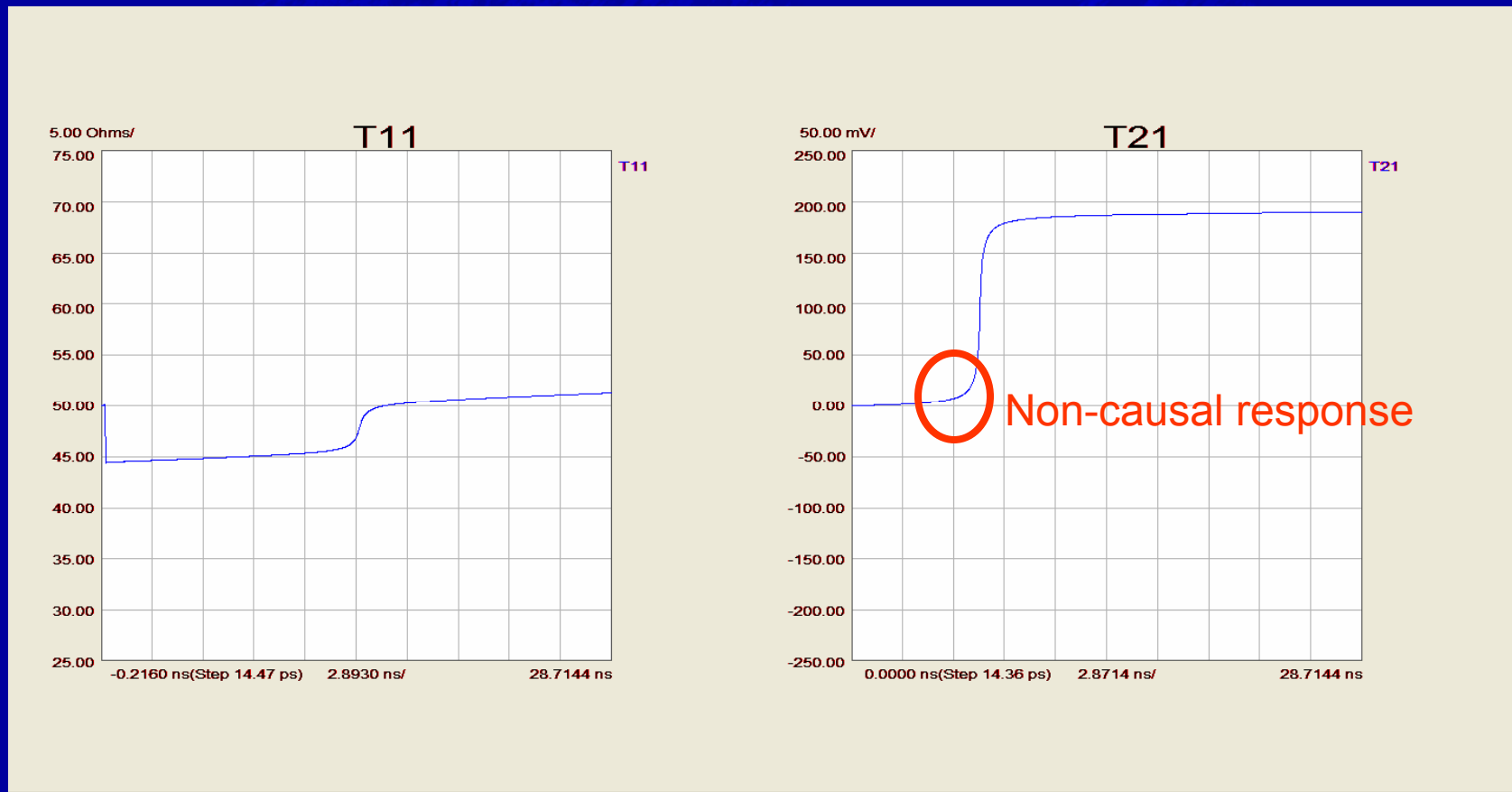
Differential impedance and transmission response transformed from measurements

Consider a Simulated Cable Response (Genysis CL1 Model)



10 MHz-20GHz, 10 MHz step, 2000 points
Dielectric constant =2, loss tangent 0.002

Transform the Simulated Frequency Domain Response to the Time Domain using PLTS



10 MHz-20GHz, 10 MHz step, 2000 points
Dielectric constant =2, loss tangent 0.002

Very reasonable looking S-Parameters can be non-causal!

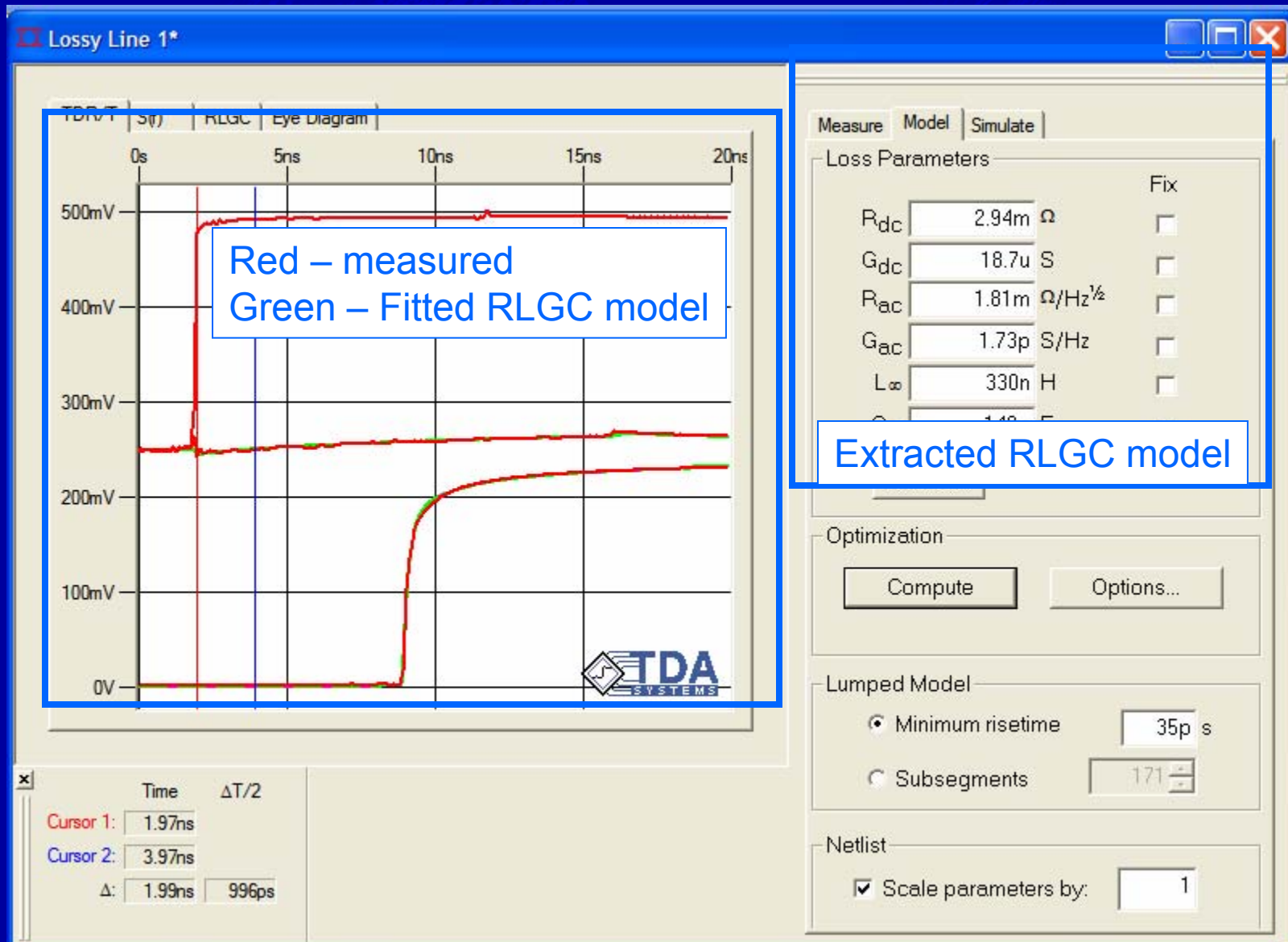
Summary on S-Parameters

- **S-Parameter files can have problems**
 - Accuracy of de-embedding
 - Causality problems with some simulation tools
 - Symmetry issues

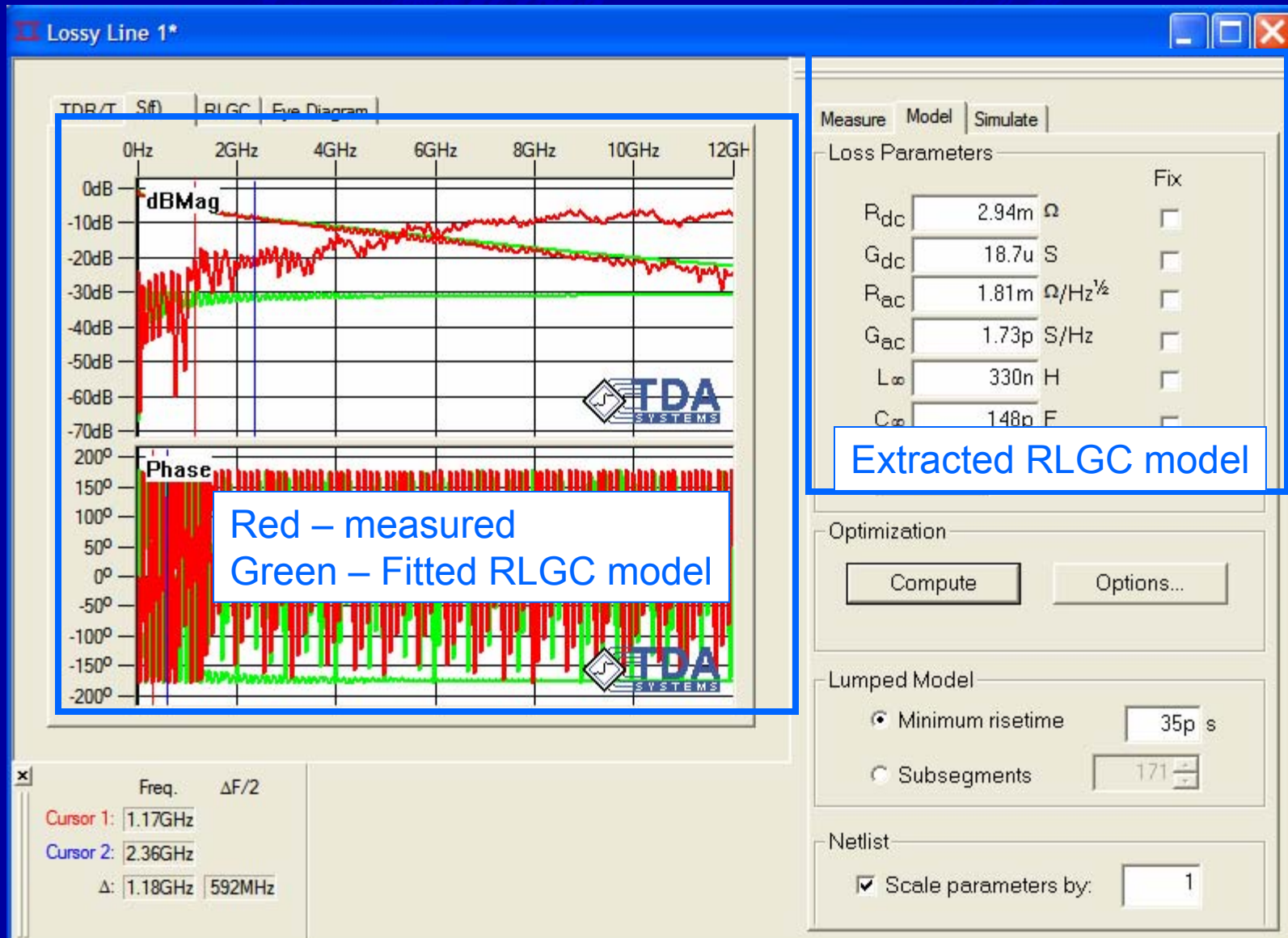
Extracting a Lossy Cable Model with IConnect

- Tektronix IConnect and MeasureXtractor
- Why we use IConnect?
 - IConnect has a “lossy line model” which fits an RLGC model to the measured data
 - Model parameters can be manually or automatically adjusted
 - Resultant model is “well behaved” in HSPICE
 - Model extracted from measured data

Extracting a Lossy Cable Model with IConnect



Extracting a Lossy Cable Model with IConnect



Using the Cable Model

- **Simulation times for lossy transmission lines can be extensive...**
- **Consider a lossy transmission line extracted from measurements using TDA IConnect**
- **We have several model types we can consider**
 - W-Element
 - S-Parameters
 - Ladder Network
- **Which one should we use?**

Using the Cable Model

- **Simulation Details**

- 5 foot length of 30AWG Twinax cable
- Model derived from measurements using TDA IConnect
- 1 psec step time and 20 nsec simulation time (20K time steps)
- Pentium IV processor, 2.8GHz clock speed

- **W-Element (HSPICE) – 18.64 seconds**

- **S-Parameter (HSPICE) – 21.36 seconds**

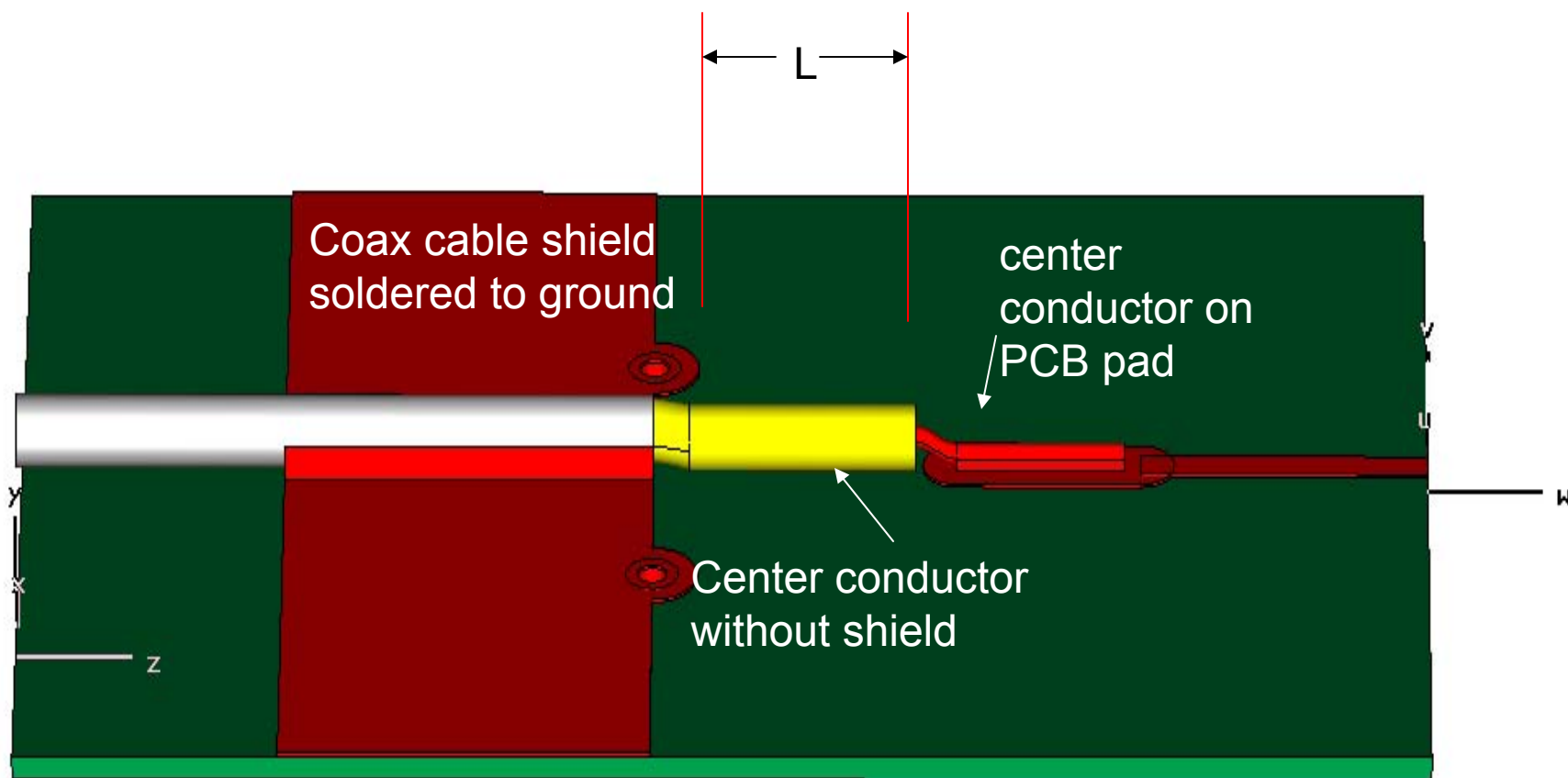
- **Ladder Model (HSPICE) – 3567 seconds (~1 hour)**

- While ladder model will run in Generic SPICE, it will take a long time

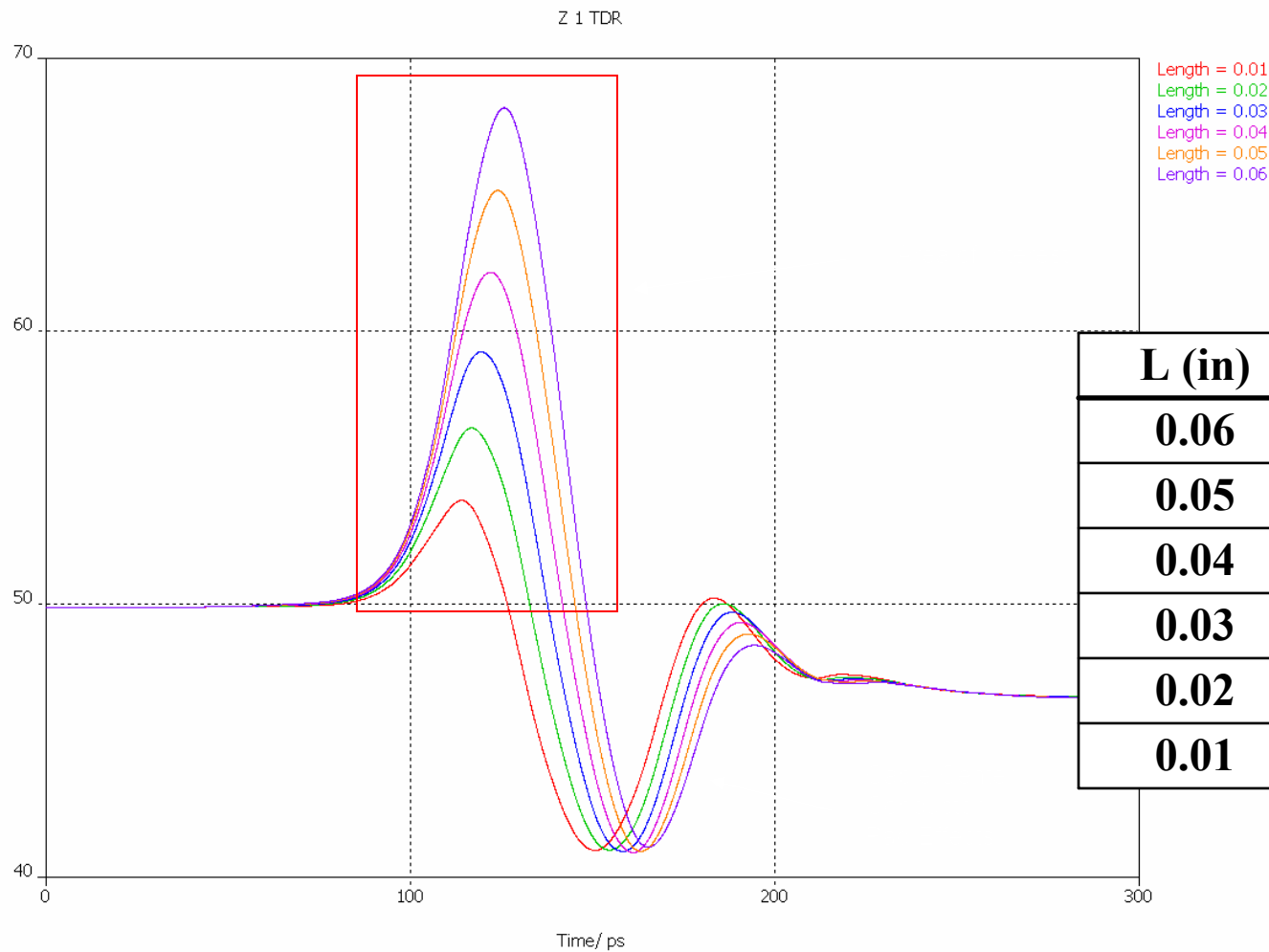
Cable Assembly Model

- **Connector and paddle board models developed using 2D FEA approach**
 - Valid for structures with minimal or well understood 3D effects
 - Yields passive, causal circuit which simulates well in SPICE
- **Cable termination response dominated by termination board**
 - Inductive effect as center conductor leaves the Coax shield
 - Capacitive effect as center conductor solders to pad on termination card

CST Microwave Simulation of Coax Cable Termination



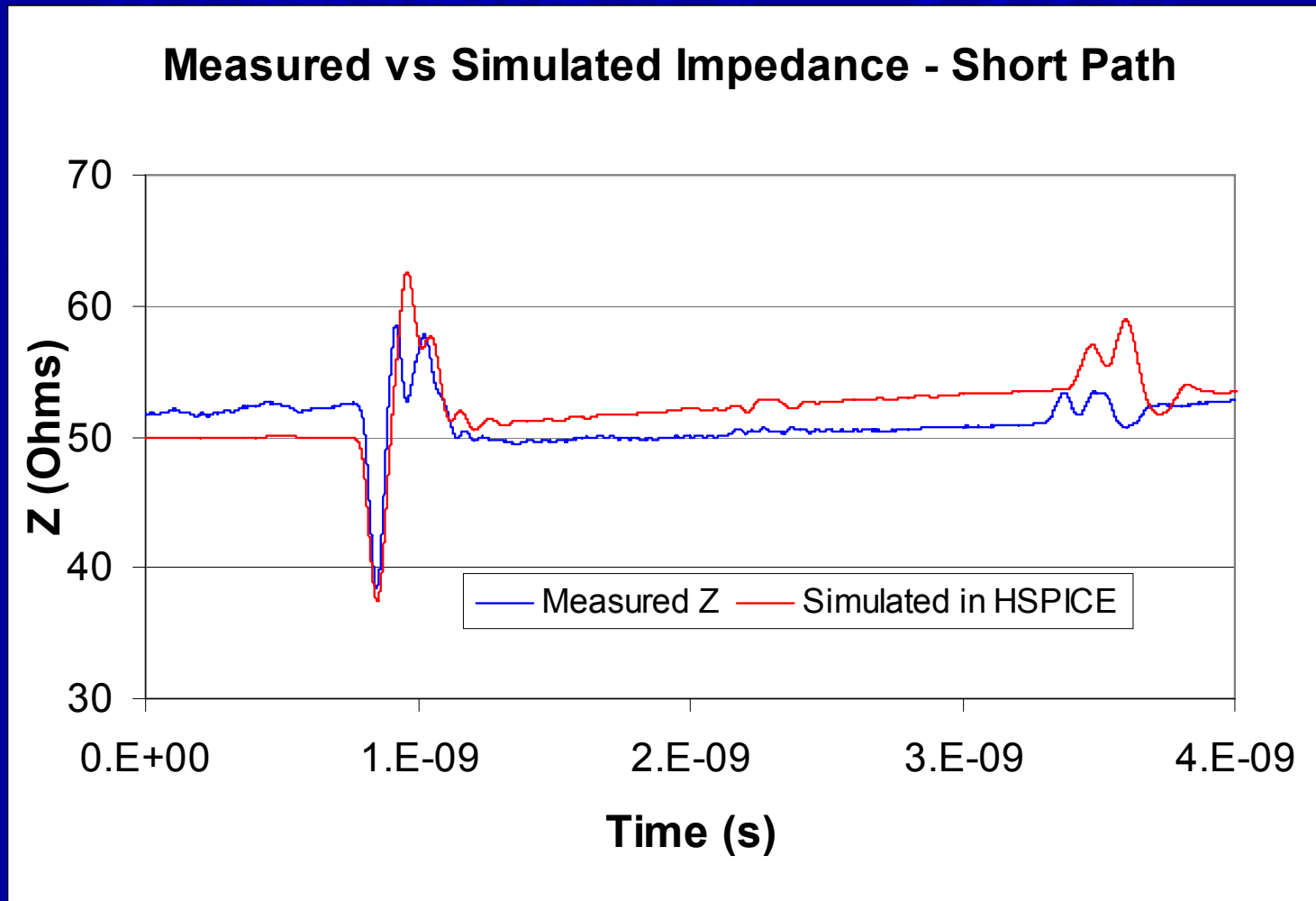
CST Microwave Simulation Results – Coax Cable Termination



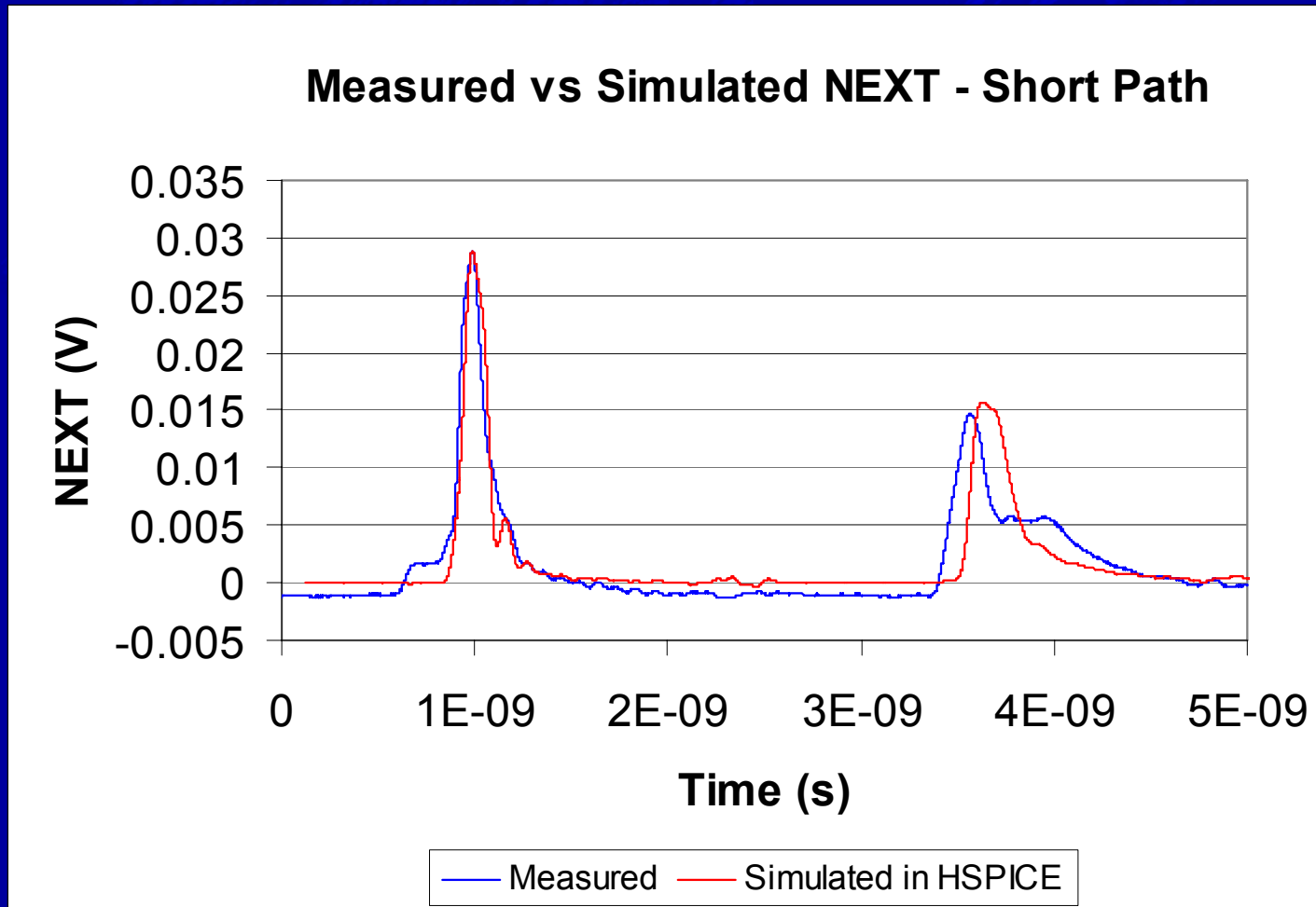
Using the Cable Assembly Model

- **Typical Assembly Model**
 - Two connector sub circuits with 20 inputs/outputs
 - Two transition board sub circuits with 20 inputs/outputs
 - 20 lossy cable sub circuits
- **A Readme file which describes**
 - How to vary the cable length
 - Pin mapping
- **Test Circuits**
 - S-Parameter simulation
 - Step response simulation for impedance/TDR data

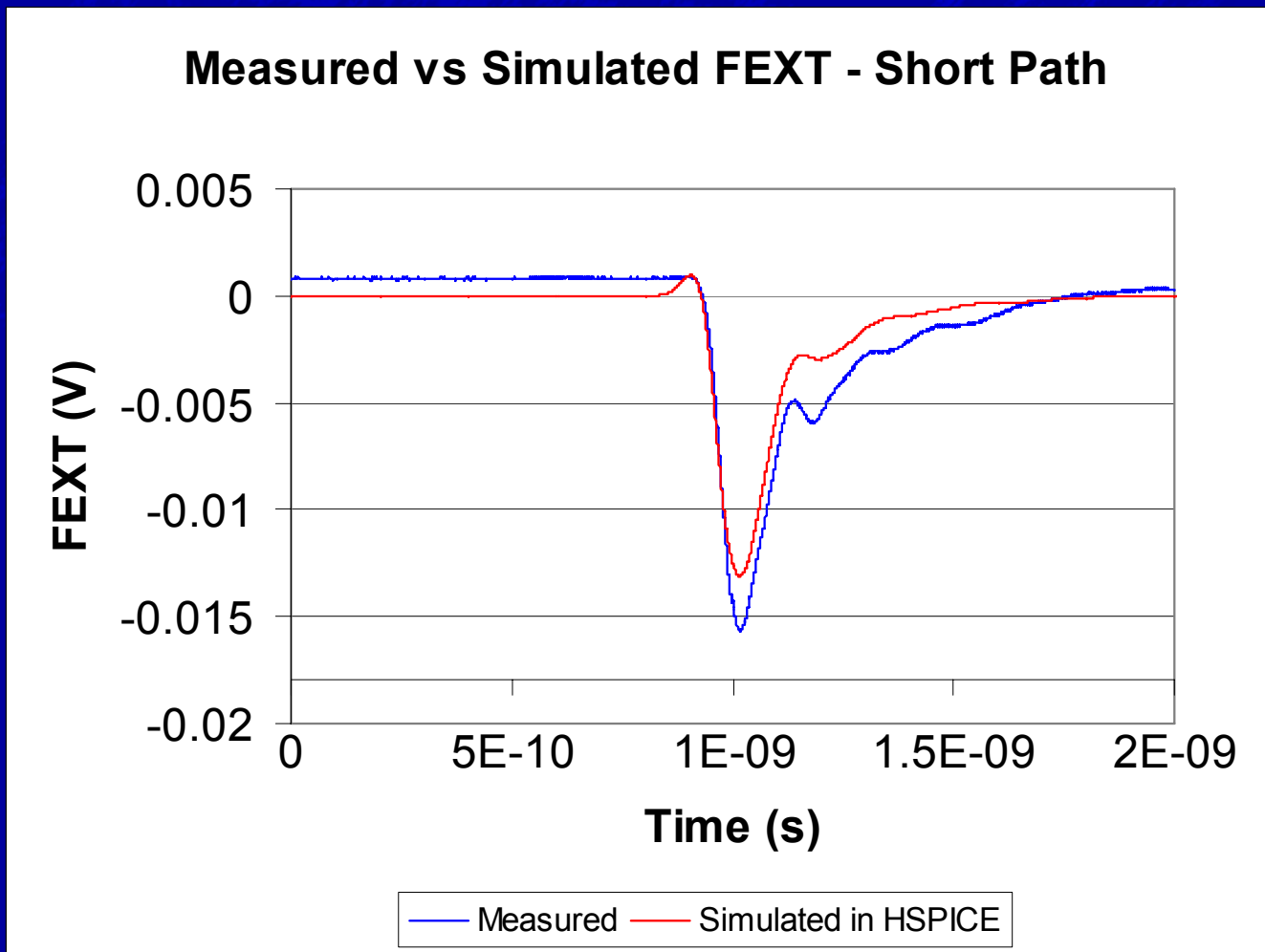
Impedance (risetime=100ps)



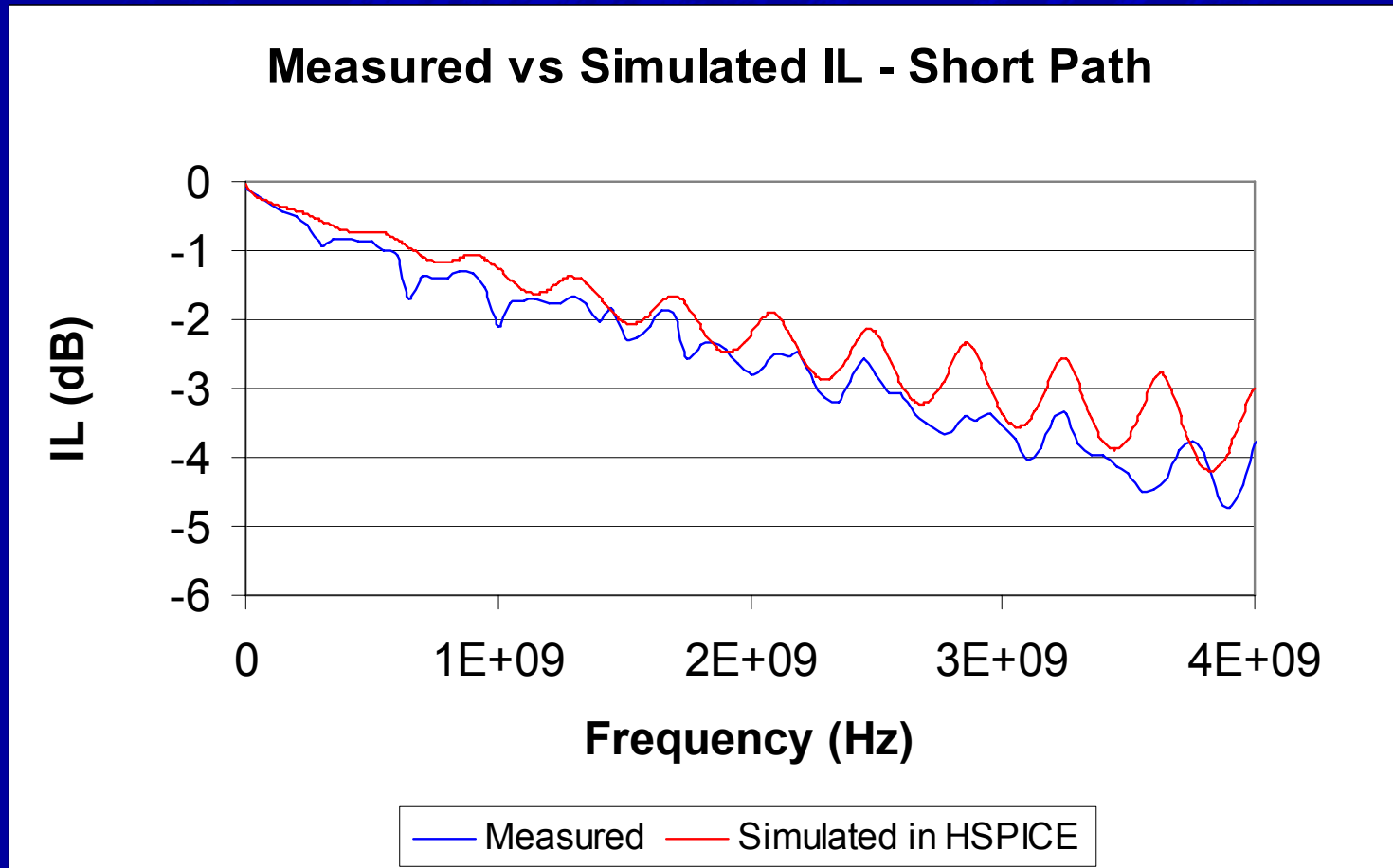
Near End Crosstalk (risetime=100ps)



Far End Crosstalk (risetime=100ps)



Insertion Loss



Summary

- Models available for download
http://www.samtec.com/signal_integrity/testing_and_simulation/spice_models.asp
- Presently have HSPICE models; other formats to follow
- Model accuracy generally within 5% compared to measured data
- Models run in HSPICE
 - With easy to follow syntax
 - Simple sub circuit calls
 - Simulation time ~10 minutes for 20 pair cable assembly

Useful References

- **Samtec Technical Papers**

- http://www.samtec.com/reference/articles/white_papers.asp

- **Lossy Transmission Lines**

- Johnson and Graham – High Speed Signal Propagation – Advanced Black Magic

- **Model Extraction via Measurements**

- <http://www2.tek.com/cmswpt/tifinder.lotr?cn=interconnect+software&lc=EN>

- <http://www.home.agilent.com/agilent/facet.jsp?c=152771.i.3&to=79830.g.0&cc=US&lc=eng&sm=g>

Thank You and Questions

- For additional questions regarding the information contained in today's presentation, please contact our Signal Integrity Group at: sig@samtec.com
- For a copy of today's presentation, please contact us at: ewebinar@samtec.com